

#### **40V 10A GATE DRIVER IN SOT26**

## **Description**

The ZXGD3006E6Q is a 40V Gate Driver for switching IGBTs and SiC MOSFETs. It can transfer up to 10A peak source/sink current into the gate for effective charging and discharging of a large capacitive load.

The ZXGD3006E6Q can drive typically 4A into the low gate impedance of an IGBT, with just 1mA input from a controller. Also, the turn-on and turn-off switching behavior of the IGBT can be individually tailored to suit an application. In particular, by defining the switching characteristics appropriately, EMI and cross conduction can be reduced.

### **Features**

- High-Gain Buffer with Typically 4A Output from 1mA Input
- 40V Supply for +20V to -18V gate driving to prevent dV/dt induced false triggering
- Emitter-Follower that is Rugged to Latch-Up / Shoot-Through Issues, and Delivers <10ns Propagation Delay Time</li>
- Optimized Pin-Out to Simplify PCB Layout and Reduce Parasitic Trace Inductances
- Near-Zero Quiescent Supply Current
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The ZXGD3006E6Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

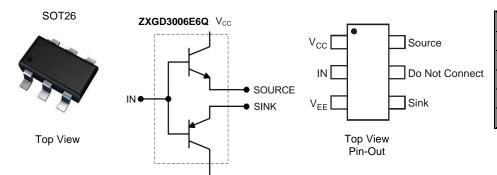
## **Applications**

Gate driving IGBTs and SiC MOSFETs in:

- DC-DC converters in electric cars
- Automotive active suspension systems
- Solar inverters
- Power supplies
- Plasma display panel power modules

### **Mechanical Data**

- Package: SOT26
- Package Material: Molded Plastic. "Green" Molding Compound.
   UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads.
   Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.018 grams (Approximate)



Pin Name	Pin Function
Vcc	Supply Voltage High
IN	Driver Input Pin
VEE	Supply Voltage Low
SOURCE	Source Current Output *
SINK	Sink Current Output *

\* Typically connect SOURCE & SINK together

### **Ordering Information** (Note 4)

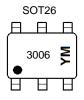
Orderable Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Paci	king
Orderable Part Number	Compliance	Warking	Reel Size (Iliches)	Tape Width (mm)	Quantity	Carrier
ZXGD3006E6QTA	Automotive	3006	7	8	3,000	Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See http://www.diodes.com/quality/lead\_free/ for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



## **Marking Information**



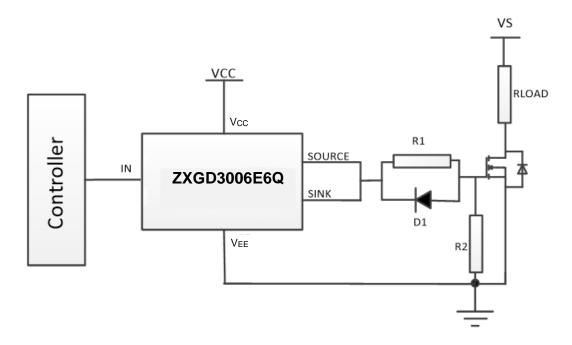
3006 = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: F = 2018)

M or  $\overline{M}$  = Month (ex: 9 = September)

Date Code Key

Year	2018		2023	2024	2025	2026	2027	2028	2029	2030	2031	2032
Code	F		K	L	М	N	Р	R	S	T	U	V
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

# **Typical Application Circuit**



R1, D1 combination can be used for variable turn on and turn off times.



## Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage, with Respect to VEE	Vcc	40	V
Input Voltage, with Respect to VEE	Vin	40	V
Output Difference Voltage (Source – Sink)	ΔV(source-sink)	±7	V
Peak Pulsed Output Current (Source – Sink)	Іом	±10	Α
Peak Pulsed Input Current	lin	±100	mA

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Notes 5 & 6) Linear Derating Factor	P <sub>D</sub>	1.1 8.8	W mW/°C
Thermal Resistance, Junction to Ambient (Notes 5 & 6)	R <sub>θJA</sub>	113	°C/W
Thermal Resistance, Junction to Lead (Note 7)	R <sub>0JL</sub>	105	
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

## ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	1,500	V	1C
Electrostatic Discharge – Charged Device Model	ESD CDM	1,000	V	IV

Notes:

- 5. For a device mounted on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state. The heatsink is split in half with the pin 1 (Vcc) and pin 3 (VEE) connected separately to each half.

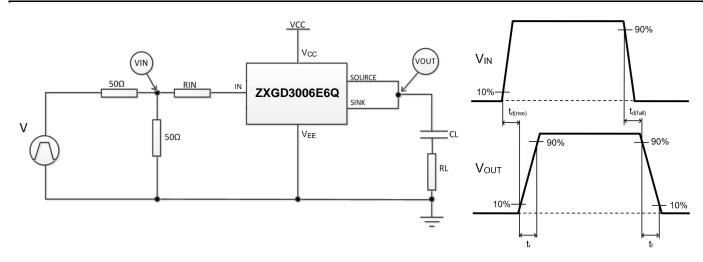
  6. For device with two active die running at equal power.
- 8. Refer to JEDEC specification JESD22-A114 and JESD22-C101.



## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

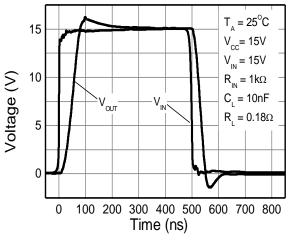
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
Output Voltage, High	VouT(hi)	Vcc - 1.0	Vcc - 0.8	_	V	VIN = VCC	
Output Voltage, Low	Vout(low)	_	VEE + 0.12	VEE + 0.3	V	$V_{IN} = V_{EE}$ $C_L = 1nF$	
Cupply Progledown Voltage	BVcc	40	_	_	V	$I_Q = 100\mu A$ , $V_{IN} = V_{CC}$	
Supply Breakdown Voltage	DVCC	40	_	_	V	$I_Q = 100\mu A$ , $V_{IN} = V_{EE} = 0V$	
Quiescent Supply Current	1-	_	_	50	~ ^	Vcc = 30V, Vin = Vcc	
Quiescent Supply Current	lq	_		50	nA	Vcc = 30V, Vin = VEE = 0V	
Peak Pulsed Source Current	I <sub>(source)M</sub>	_	4.0	_	Α	$V_{CC} = 5V$ , $I_{IN} = 1mA$ , $V_{OUT} = 0V$	
Peak Pulsed Sink Current	I <sub>(sink)M</sub>	_	3.8	_	А	$V_{CC} = 5V$ , $I_{IN} = -1mA$ , $V_{OUT} = 5V$	
Source Current with Varying Input Resistances	Isource	_	6.4 5.5 3.9 2.2 0.44		A	$ \begin{aligned} & R_{IN} = 200\Omega \\ & R_{IN} = 1k\Omega \\ & R_{IN} = 10k\Omega \\ & R_{IN} = 100k\Omega \\ & R_{IN} = 1000k\Omega \end{aligned}  \begin{aligned} & V_{CC} = 15V, \ V_{EE} = 0V \\ & V_{IN} = 15V \\ & C_{L} = 100nF, \ R_{L} = 0.18\Omega \end{aligned} $	
Sink Current with Varying Input Resistances	Isink	_	7.7 6.5 4.4 2.3 0.46	_	А	$ \begin{aligned} R_{IN} &= 200\Omega \\ R_{IN} &= 1k\Omega \\ R_{IN} &= 10k\Omega \\ R_{IN} &= 100k\Omega \\ R_{IN} &= 1000k\Omega \end{aligned}  \begin{aligned} &V_{CC} &= 15V, \ V_{EE} = 0V \\ &V_{IN} &= 15V \\ &C_{L} &= 100nF, \ R_{L} = 0.18\Omega \end{aligned} $	
Switching Times with Low Load Capacitance $C_L = 10nF$	t <sub>d(rise)</sub> tr t <sub>d(fall)</sub> tf	_	8 48 16 35		ns	$V_{CC} = 15V, V_{EE} = 0V$ $V_{IN} = 0 \text{ to } 15V$ $R_{IN} = 1k\Omega$ $CL = 10nF, RL = 0.18\Omega$	
Switching Times with High Load Capacitance C <sub>L</sub> = 100nF	td(rise) t <sub>r</sub> td(fall) tf	_	46 419 47 467	_	ns	$V_{CC} = 15V$ , $V_{EE} = 0V$ $V_{IN} = 0$ to 15V $R_{IN} = 1kΩ$ $C_L = 100nF$ , $R_L = 0.18Ω$	
Switching Times with Asymmetric Source and Sink Resistors	t <sub>d(rise)</sub> t <sub>r</sub> t <sub>d(fall)</sub> t <sub>f</sub>	_	27 208 11 53		ns	$\label{eq:VCC} \begin{split} &V_{CC}=20V,V_{EE}=-18V\\ &V_{IN}=-18Vto20V\\ &R_{IN}=1k\Omega\\ &C_L=10nF,R_L=0.18\Omega\\ &R_{SOURCE}=4.7\Omega,R_{SINK}=0\Omega(\text{See page 7}). \end{split}$	

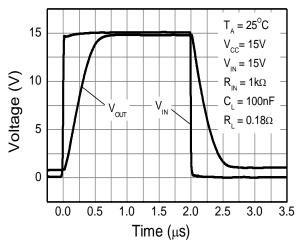
# **Switching Test Circuit and Timing Diagram**





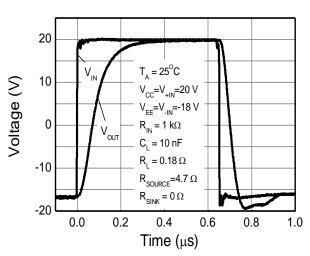
## Typical Switching Characteristics (@TA = +25°C, unless otherwise specified.)

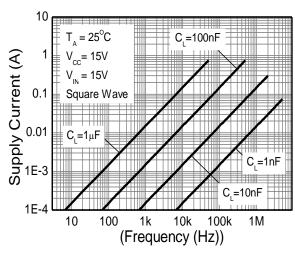




# **Switching Speed**

**Switching Speed** 



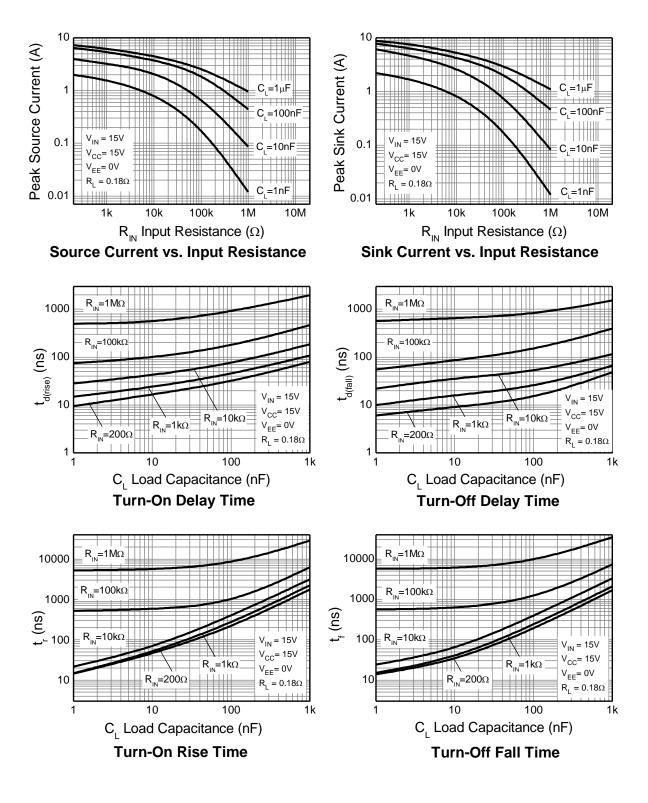


Switching Speed
Asymmetric Source and Sink Resistance

**Supply Current** 



## Typical Switching Characteristics (@TA = +25°C, unless otherwise specified.)

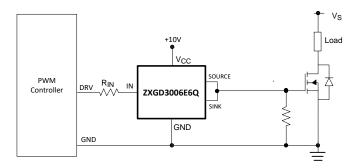




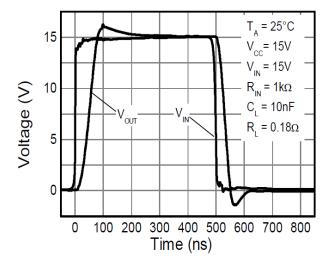
## **Circuit Examples**

### ZXGD3006E6Q Driving a MOSFET

Application example of the ZXGD3006E6Q driving the gate of a MOSFET from 0 to +15V.



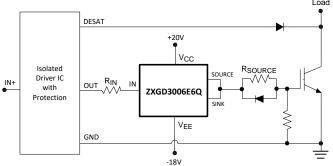
**Switching Time Characteristic** 



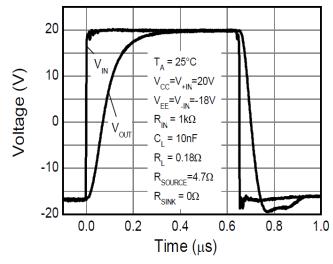
Symmetric Source and Sink Resistors

### ZXGD3006E6Q Driving an IGBT

Application example of ZXGD3006E6Q driving the gate of an IGBT with independent  $t_{\rm ON}$  and  $t_{\rm OFF}$  using asymmetric R<sub>SOURCE</sub> and R<sub>SINK</sub>. In addition, the gate is driven negative to -18V to prevent dV/dt induced false triggering.



**Switching Time Characteristic** 

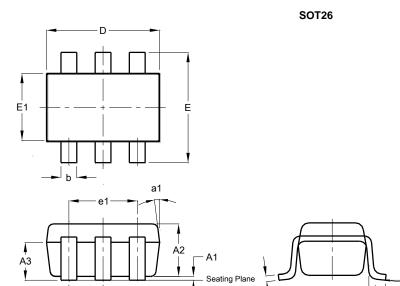


Asymmetric Source and Sink Resistors



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

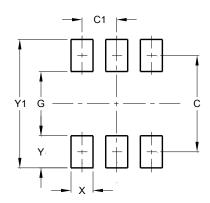


SOT26						
Dim	Min	Max	Тур			
A1	0.013	0.10	0.05			
A2	1.00	1.30	1.10			
А3	0.70	0.80	0.75			
b	0.35	0.50	0.38			
С	0.10	0.20	0.15			
D	2.90	3.10	3.00			
е	-	-	0.95			
e1	-	-	1.90			
Е	2.70	3.00	2.80			
E1	1.50	1.70	1.60			
L	0.35	0.55	0.40			
а	-	-	8°			
a1	-	-	7°			
All	Dimen	sions	in mm			

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SOT26



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
V1	2.20



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